

TOSHIBA PHOTOCOUPLER GaAs IRED & PHOTO-TRIAC

TLP3051(S),TLP3052(S)

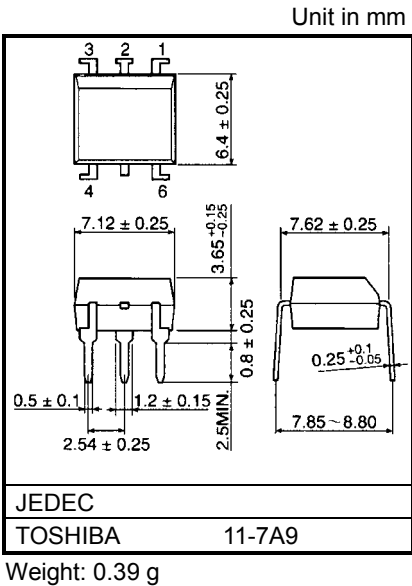
OFFICE MACHINE
HOUSEHOLD USE EQUIPMENT
TRIAC DRIVERSOLID STATE RELAY

The TOSHIBA TLP3051(S) and TLP3052(S) consists of a photo-triac optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

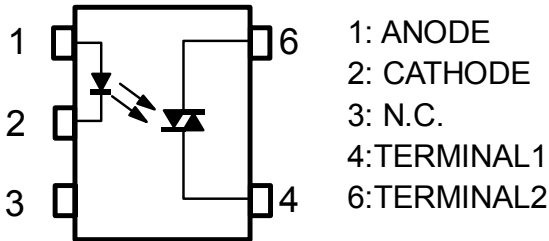
- Peak Off-State Voltage : 600V(Min)
 - Trigger LED Current : 15mA(Max)TLP3051
10mA(Max)TLP3052
 - On-State Current : 100mA(Max)
 - Isolation Voltage : 5000Vrms(Min)
 - UL Recognized :UL1577,File No.E67349
 - SEMKO Approved :SS EN60065
SS EN60950, File No.9841102
 - BSI Approved :BS EN60065, File No.8385
BS EN60950, File No.8386
- Option(D4)type
VDE Approved :DIN VDE0884
Certificate No.68329
- Maximum Operating Insulation Voltage :890V_{PK}
Highest Permissible Over Voltage :8000 V_{PK}

(Note)When a VDE0884 approved type is needed,
please designate the “Option(D4)”

• Construction Mechanical Rating		
	7.62 mm pich standard type	10.16 mm pich TLPXXXF type
Creepage Distance	7.0 mm (Min)	8.0 mm (Min)
Clearance	7.0 mm (Min)	8.0 mm (Min)
Insulation Thickness	0.5 mm (Min)	0.5 mm (Min)



PIN CONFIGURATION (TOP VIEW)



MAXIMUM RATINGS(Ta=25°C)

CHARACTERISTIC			SYMBOL	RATING	UNIT
LED	Forward Current		I _F	50	mA
	Forward Current Derating (Ta≥53℃)		ΔI _F /℃	-0.7	mA /℃
	Peak Forward Current (100μs pulse, 100pps)		I _{FP}	1	A
	Power Dissipation		P _D	100	mW
	Power Dissipation Derating (Ta≥25℃)		ΔP _D /℃	-1.0	mW/℃
	Reverse Voltage		V _R	5	V
	Junction Temperature		T _j	125	℃
DETECTOR	Off-State Output Terminal Voltage		V _{DRM}	600	V
	On-State RMS Current	Ta=25℃	I _{T(RMS)}	100	mA
		Ta=70℃		50	
	On-State Current Derating (Ta≥25℃)		ΔI _T /℃	-1.1	mA /℃
	Peak On-State Current (100μs pulse, 120pps)		I _{TP}	2	A
	Peak Nonrepetitive Surge Current (Pw=10ms,DC=10%)		I _{TSM}	1.2	A
	Power Dissipation		P _D	300	mW
	Power Dissipation Derating (Ta≥25℃)		ΔP _D /℃	-4.0	mW/℃
	Junction Temperature		T _j	115	℃
Operating Temperature Range			T _{opr}	-40~100	℃
Storage Temperature Range			T _{stg}	-55~150	℃
Lead Soldering Temperature (10s)			T _{sol}	260	℃
Total Package Power Dissipation			P _T	330	mW
Total Package Power Dissipation Derating (Ta≥25℃)			ΔP _T /℃	-4.4	mW /℃
Isolation Voltage (AC,1min. , R.H.≤60%) (Note 2)			BV _S	5000	Vrms

(Note 2) Device considered a two terminal device : Pins1,2 and 3 shorted together and pin4 and pin6 shorted together.

RECOMMENDED OPERATING CONDITIONS

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V_{AC}	—	—	240	V_{ac}
Forward Current	I_F^*	15	20	25	mA
Peak On-State Current	I_{TP}	—	—	1	A
Operating Temperature	T_{opr}	-25	—	85	°C

*In The case of TLP3052

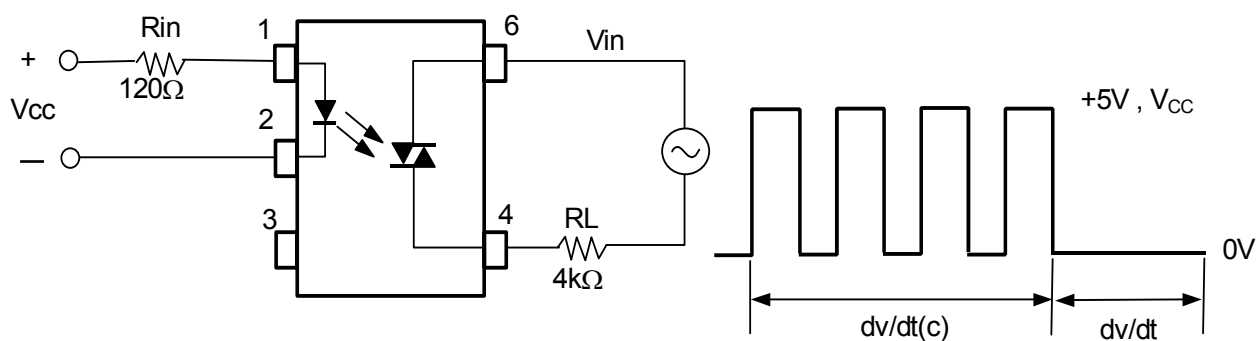
INDIVIDUAL ELECTRICAL CHARACTERISTICS(Ta=25°C)

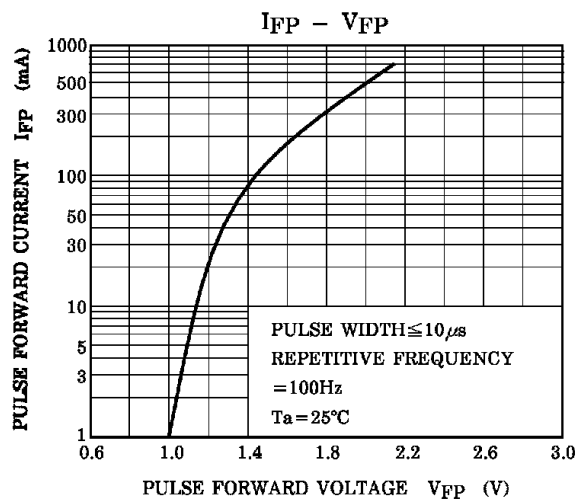
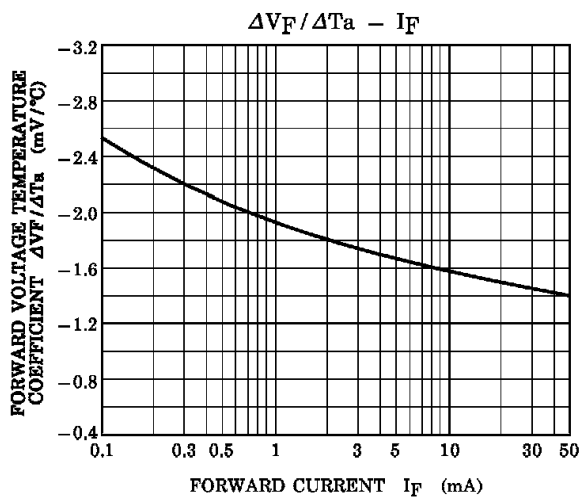
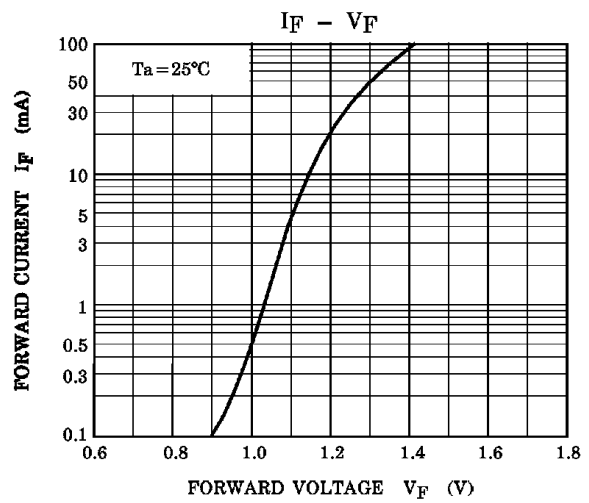
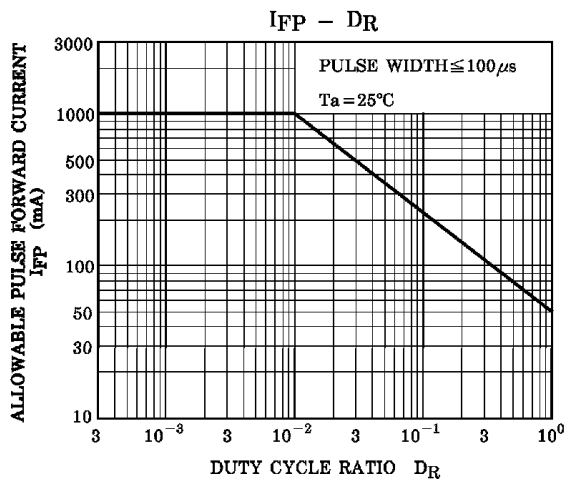
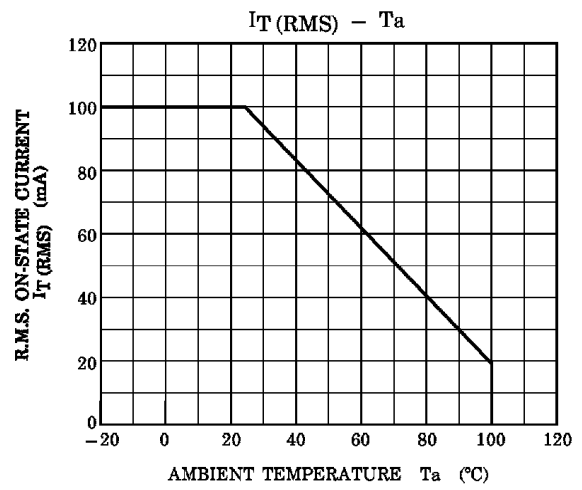
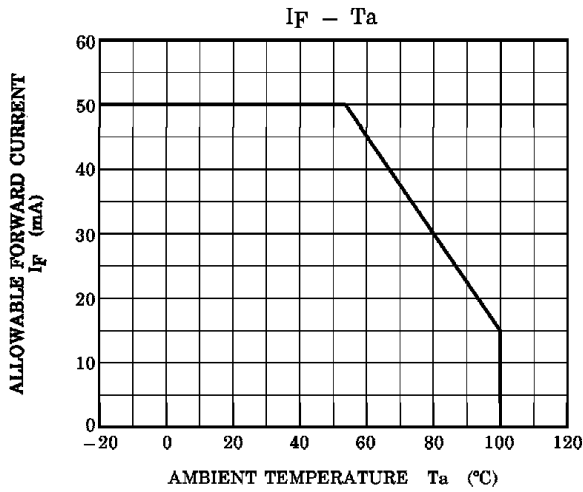
CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
LED	Forward Voltage	V_F	$I_F = 10 \text{ mA}$	1.0	1.15	1.3	V
	Reverse Current	I_R	$V_R = 5 \text{ V}$	—	—	10	μA
	Capacitance	C_T	$V = 0, f=1\text{MHz}$	—	30	—	pF
DETECTOR	Peak Off-State Current	I_{DRM}	$V_{\text{DRM}}=600\text{V}$	—	10	1000	nA
	Peak On-State Voltage	V_{TM}	$I_{\text{TM}}=100\text{mA}$	—	1.7	3.0	V
	Holding Current	I_H	—	—	1.0	—	mA
	Critical Rate of Rise of Off-State Voltage	dv/dt	$V_{\text{in}}=240\text{Vrms}, T_a=85^\circ\text{C}$ (Note3)	—	500	—	$\text{V}/\mu\text{s}$
	Critical Rate of Rise of Commutating Voltage	$dv/dt(c)$	$V_{\text{in}}=60\text{Vrms}, I_T=15\text{mA}$ (Note3)	—	0.2	—	$\text{V}/\mu\text{s}$

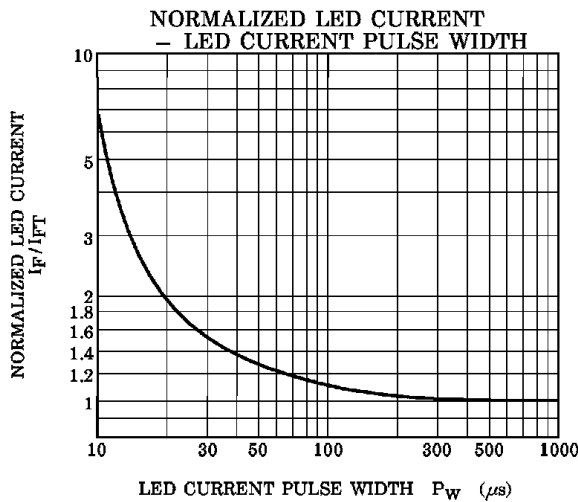
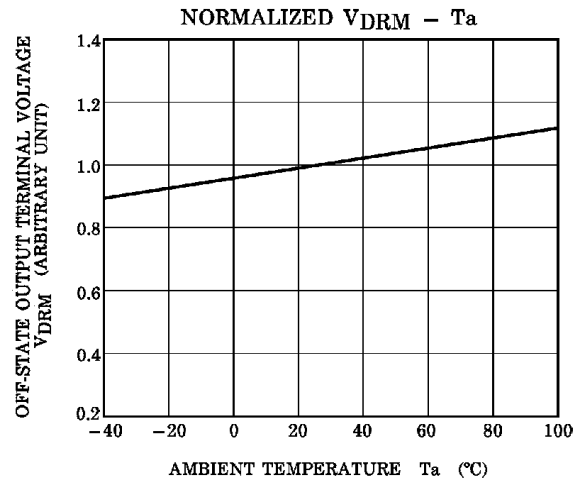
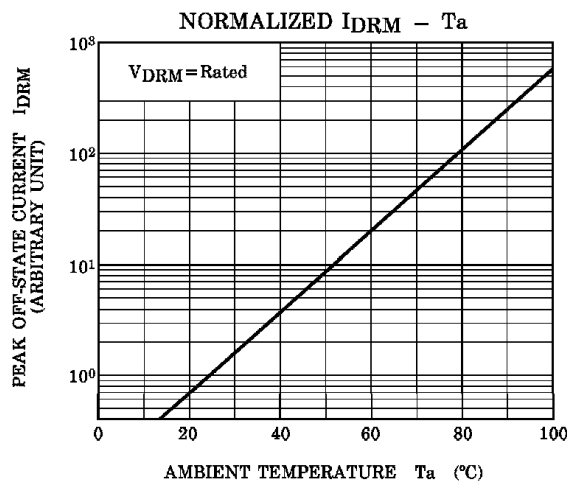
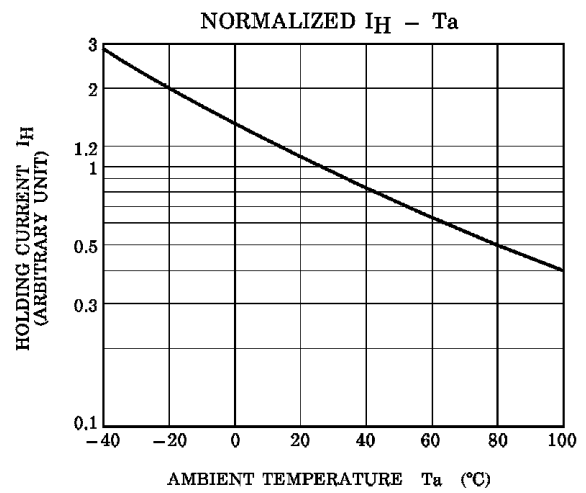
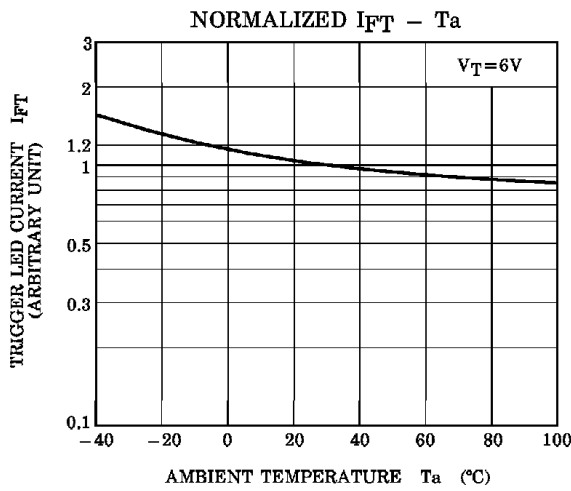
COUPLED ELECTRICAL CHARACTERISTICS(Ta=25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Trigger LED Current	TLP3051	I_{FT}	$V_T=6\text{V}$	—	—	15	mA
	TLP3052			—	5	10	
Capacitance (Input to Output)		C_S	$V_S=0, f=1\text{MHz}$	—	0.8	—	pF
Isolation Resistance		R_S	$V_S=500\text{V}(\text{R.H.}\leq 60\%)$	5×10^{10}	10^{14}	—	Ω
Isolation Voltage		BV_S	AC, 1minute	5000	—	—	Vrms
			AC, 1second, in oil	—	10000	—	
			DC, 1minute, in oil	—	10000	—	Vdc

(Note 3) dv/dt TEST CIRCUIT







RESTRICTIONS ON PRODUCT USE

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